



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

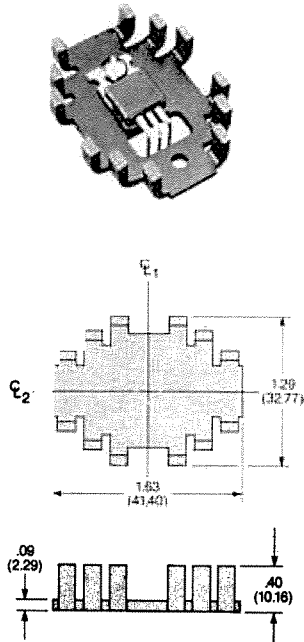
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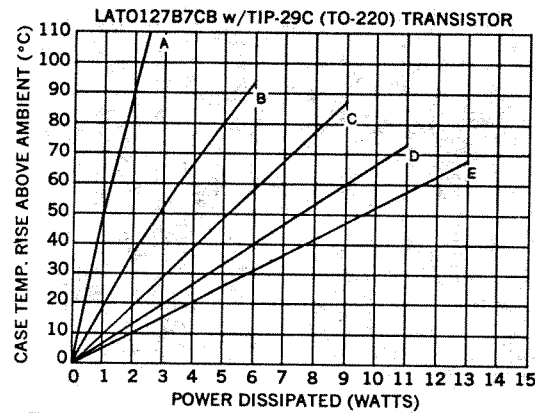
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



## LA-B7 Series



Dimensions are for reference use only. Contact IERC for dimensions with tolerances or standard part drawings.



### DESCRIPTION OF CURVES

- A. N.C. Horiz. Device Only Mounted to G-10.
- B. N.C. Horiz. & Vert. With Dissipator.
- C. 200 FPM w/Diss.
- D. 500 FPM w/Diss.
- E. 1000 FPM w/Diss.

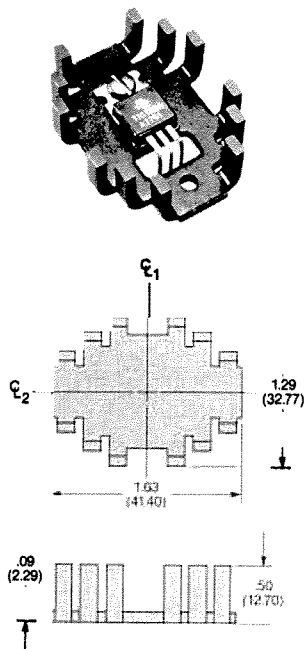
- Thermal Resistance Case to Sink is 0.9-1.1 °C/W w/Joint Compound.
- Derate 0.6 °C/watt for unplated part in natural convection only.
- Derate 3.0 °C/watt for Insulube® part in natural convection only.

### Ordering Information

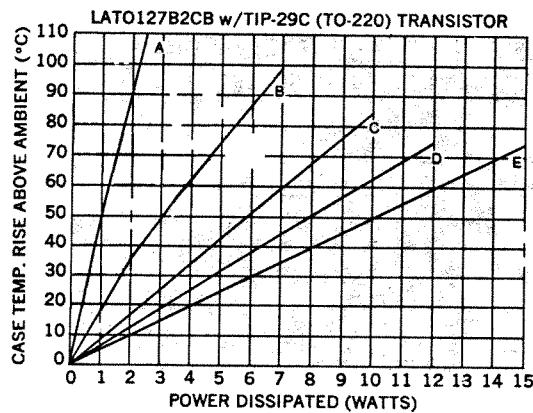
IERC PART NO.				Semiconductor Accommodated	Hole patt. ref. no. (see pg. 2-27)	Max. Weight (Grams)
Unplated	Comm'l. Black Anodize	Mil. Black Anodize	Insulube® 448			
LA000B7U	LA000B7CB	LA000B7B	LA000B7	Undrilled	—	7.8
LATO126B7U	LATO126B7CB	LATO126B7B	LATO126B7	TO-126	2	7.8
LATO127B7U	LATO127B7CB	LATO127B7B	LATO127B7	TO-127, TO-220	3	7.8
LA394B7U	LA394B7CB	LA394B7B	LA394B7	Universal	4	7.8

Note: See page iv for other finishes.

## LA-B2 Series



Dimensions are for reference use only. Contact IERC for dimensions with tolerances or standard part drawings.



### DESCRIPTION OF CURVES

- A. N.C. Horiz. Device Only Mounted to G-10.
- B. N.C. Horiz. & Vert. With Dissipator.
- C. 200 FPM w/Diss.
- D. 500 FPM w/Diss.
- E. 1000 FPM w/Diss.

- Thermal Resistance Case to Sink is 0.9-1.1 °C/W w/Joint Compound.
- Derate 0.6 °C/watt for unplated part in natural convection only.
- Derate 3.0 °C/watt for Insulube® part in natural convection only.

### Ordering Information

IERC PART NO.				Semiconductor Accommodated	Hole patt. ref. no. (see pg. 2-27)	Max. Weight (Grams)
Unplated	Comm'l. Black Anodize	Mil. Black Anodize	Insulube® 448			
LA000B2U	LA000B2CB	LA000B2B	LA000B2	Undrilled	—	8.8
LATO126B2U	LATO126B2CB	LATO126B2B	LATO126B2	TO-126	2	8.8
LATO127B2U	LATO127B2CB	LATO127B2B	LATO127B2	TO-127, TO-220	3	8.8
LA394B2U	LA394B2CB	LA394B2B	LA394B2	Universal	4	8.8

Note: See page iv for other finishes.